IEC/PAS 61189-3-913

Edition 1.0 2011-01

PUBLICLY AVAILABLE SPECIFICATION

PRE-STANDARD

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inside

Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 3-913: Test methods for interconnection structures (printed boards) – Electronic circuit board for high-brightness LEDs

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

PRICE CODE X

ICS 31.180

ISBN 978-2-88912-343-8

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IEC-PAS 61189-3-913 was submitted by the JPCA (Japan Electronics Packaging and Circuits Association) and has been processed by IEC technical committee 91: Electronics assembly technology.

It is based on JPCA-TMC-LED02T-2010. It is published as a double-logo IEC/ JPCA PAS.

The text of this PAS is based on the following document:	This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document
Draft PAS	**Report on voting**
91/928/PAS	91/943A/RVD

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A list of all the parts in the IEC 61189 series, under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

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Part 3-913: Test methods for interconnection structures (printed boards) – Electronic circuit board for high-brightness LEDs

1 Scope

This standard specifies the test methods of the electronic circuit board for high-brightness LEDs (hereafter described as electronic circuit board).

NOTE Reference documents to this standard are listed in Clause 11 Normative references and in the Bibliography.